

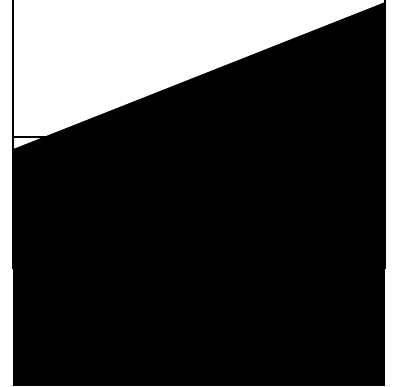
	9144030070855050X9		
			0755-33810388
	<p style="text-align: center;">(Printed Circuit Board PCB)</p> <p>(High Density Interconnection HDI)</p> <p>(Flexible Printed Circuit FPC)</p> <p style="text-align: center;">/</p> <p>ISO9001 ISO14001 ISO14064 ISO45001</p> <p>ISO50001 QC080000</p>		



				39 ()				
				10 ()				
			/	(mg/m ³)		mg/m ³		
				0.007	0.03	7		
				0.35	1.676	30		
				0.022	0.077	30		
				0.55	2.61	200		
				0.03	0.0071	0.5		
				VOCs	3.7	3.69	80	
				0	0	1.0		
				3.038	3.61	120		
				21.9	0.647	150		
				0.79	0.073	50		
				0	0	20		
				0	/			
				0	0	8.5		
				2.418	4.071	120		
			GB21900-2008 5 VOCs DB44/815-2010 2 DB44/765-2019 2 DB44/27-2001 2 DB44/ 2367-2022 1					

			()	()		
			340.1	340.1		
			5173.548	5173.548		

1560.373 1560.373



			0.55954	0.55954	
			1840.79	1840.79	
			915.43	915.43	5.
			1.08434	1.08434	
			0.38	0.38	
			32.84	32.84	6.
			164.2	164.2	
			146.64	148.64	
			149.23	149.23	
			6.49	6.49	7.
			0.05	0.05	
			64.642	64.642	
			186.357	186.357	8.
		()	16.123	16.123	
		FPC	4.854	4.854	

9.

PP

10.

			0.33	0.33	1.
			1.425	1.425	2.
			2147.58	2147.58	3.
			0.02	0.02	4.
			5.51	5.51	5.
			18.34	18.34	6. ()
			0.41	0.41	
		(18-40L)	4.81	4.81	
			1.612	1.612	
			166.468	166.468	

			Leq	Leq	Leq	Leq		
	1	1#	61	53	65	55		
	1	2#	59	54				
	1	3#	58	53				
	1	4#	61	53				
	1	1#	59	54				
	1	2#	62	53				
	1	3#	61	53				
	1	4#	60	53				

			2006	12	12000 /
			2006	12	153.5 /
		()	2018	6	26.6 /
			2021	9	8000 /
			2023	6	30000 /

()		2005-12 -23	[2005]213			
()		2006-08 -10	[2006]102 172			
() 2017		2009-09 -08	[2009]100 917		2007/ 7/19	[2007] 075
					2009/ 2/9	[2009] 021
					2011/4 /11	[2011] 026
		2018-04 -28	2018 600129		2021/ 3/17	
					2022/ 8/4	
		2020-11 -10	2020 000193		2022/ 5/21	

		2022-12 -09	[2022]000 033			

			2023-1-17 2022-9-14
	1		
	2		
	3		
	3.1		

«

	<p>1. COD pH</p> <p>2. 2018 5 15 (2012)</p> <p>3. 440 RMB</p>
	<p>2018 9</p> <p>(SZDB/Z 151-2015) 5</p>

1.

2. 2016 41

2024 4 3